

less than 10° C. than that of the first adhesion layer, and is 80° C. (exclusive) to 200° C. (inclusive).

22. The method according to claim 20, wherein said thinning the element formation substrate is performed after said opposing the element formation substrate with the opposing substrate, and said bonding the plastic substrate to the element formation substrate is performed after said thinning the element formation substrate.

23. The method according to claim 20, further comprising thinning the opposing substrate made of glass after said opposing the element formation substrate with the opposing substrate.

24. A display device manufacturing method comprising:

forming active elements in one-to-one relation with pixels on an element formation substrate made of glass;

thinning the element formation substrate by polishing after said forming the active elements;

bonding a first plastic substrate to the element formation substrate at least in a pixel region via an adhesion layer, and bonding a third plastic substrate to the element formation substrate or the first plastic substrate in a peripheral region outside of the pixel region via the adhesion layer; and

opposing the element formation substrate with an opposing substrate to form a display part driven by the active elements and displaying an image in units of pixels.

25. The method according to claim 24, wherein a linear expansion coefficient of the first plastic substrate is 30 ppm/° C. (inclusive) to 300 ppm/° C. (inclusive), and a linear expansion coefficient of the third plastic substrate is not more than $\frac{2}{3}$ that of the first plastic layer, and is 1 ppm/° C. (inclusive) to 30 ppm/° C. (exclusive).

26. The method according to claim 24, wherein said thinning the element formation substrate is performed after said opposing the element formation substrate with the opposing substrate, and said bonding the first and the third plastic substrate to the element formation substrate is performed after said thinning the element formation substrate.

27. The method according to claim 24, further comprising thinning the opposing substrate made of glass after said opposing the element formation substrate with the opposing substrate.

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